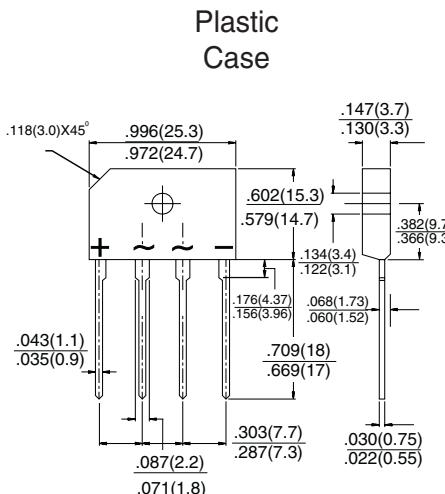


## 4.0 Amp. Glass Passivated Bridge Rectifier

<p><b>Plastic Case</b></p>  <p><b>Mounting Instructions</b></p> <ul style="list-style-type: none"> <li>• High temperature soldering guaranteed: 260 °C – 10 sc.</li> <li>• Recommended mounting torque: 8 Kg.cm.</li> </ul>	<p><b>Voltage</b> 400 to 1000 V.</p> <p><b>Current</b> 4.0</p> <p style="text-align: center;"></p> <p><b>• Glass Passivated Junction Chips.</b></p> <ul style="list-style-type: none"> <li>• Lead and polarity identifications.</li> <li>• Case: Molded Plastic.</li> <li>• Ideal for printed circuit board (P.C.B.).</li> <li>• High surge current capability.</li> <li>• The plastic material carries U/L recognition 94 V-O.</li> </ul>
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Maximum Ratings, according to IEC publication No. 134

		D3SB 40	D3SB 60	D3SB 80	D3SB 100
$V_{RRM}$	Peak recurrent reverse voltage (V)	400	600	800	1000
$V_{RMS}$	Maximum RMS voltage (V)	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink		4.0 A at 115°C Tc. 3.0 A at 40 °C		
$I_{FSM}$	10 ms. peak forward surge current (Jedec Method)			120 A	
$V_{DIS}$	Dielectric strength (terminals to case, AC 1 min.)			2000 V	
$I^2t$	Current squared time (rating for fusing) (1ms.<t<10ms. Tc = 25°C)			60 A <sup>2</sup> sec	
$T_j$	Operating temperature range			– 55 to + 150 °C	
$T_{stg}$	Storage temperature range			– 55 to +150 °C	

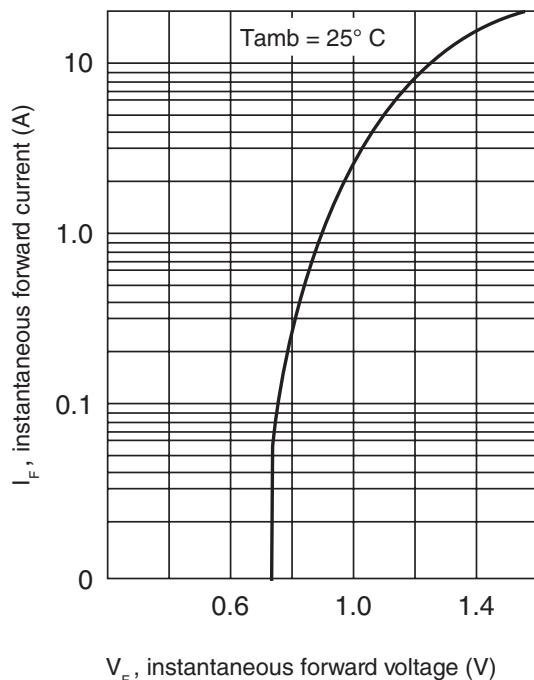
### Electrical Characteristics at Tamb = 25°C

$V_F$	Max. forward voltage drop per diode at $I_F = 2.0 \text{ A}$ $I_F = 4.0 \text{ A}$	1.00V 1.10V
$I_R$	Max. instantaneous reverse current at $V_{RRM}$	5µA
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	5.5 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W

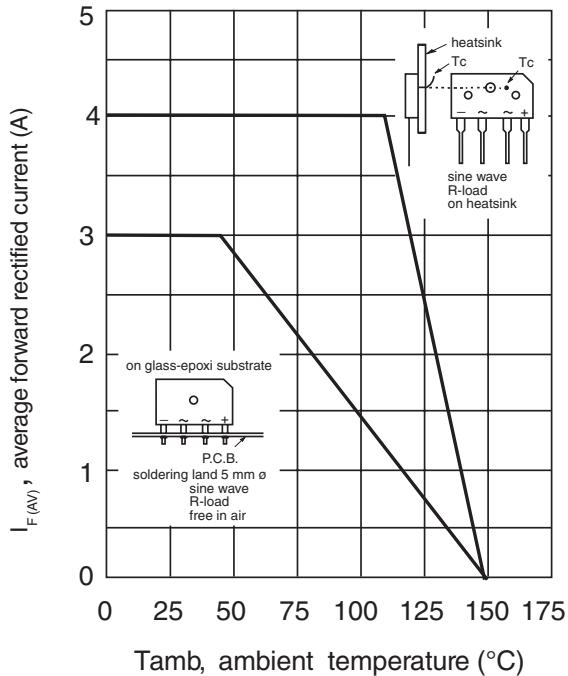
## 4 Amp. Glass Passivated Bridge Rectifier

### Characteristic Curves

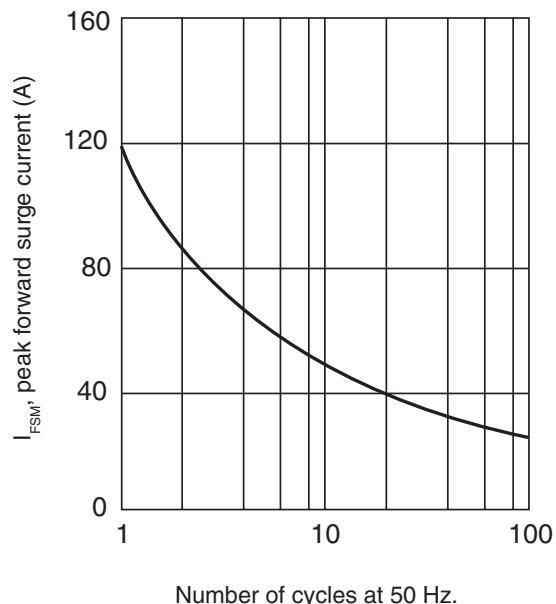
TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK  
FORWARD SURGE CURRENT



Number of cycles at 50 Hz.